

**E1UGA30-15.000M****ITEM DESCRIPTION**


Quartz Crystal Resonator HC49/US Short Thru-Hole 2.5mm Height Metal Resistance Weld Seal 15.000MHz  $\pm 15$ ppm at 25°C,  $\pm 30$ ppm over 0°C to +70°C 30pF Parallel Resonant

**ELECTRICAL SPECIFICATIONS**

<b>Nominal Frequency</b>	15.000MHz
<b>Frequency Tolerance/Stability</b>	$\pm 15$ ppm at 25°C, $\pm 30$ ppm over 0°C to +70°C
<b>Aging at 25°C</b>	$\pm 5$ ppm/year Maximum
<b>Load Capacitance</b>	30pF Parallel Resonant
<b>Shunt Capacitance</b>	7pF Maximum
<b>Equivalent Series Resistance</b>	60 Ohms Maximum
<b>Mode of Operation</b>	AT-Cut Fundamental
<b>Drive Level</b>	1mWatt Maximum
<b>Storage Temperature Range</b>	-40°C to +125°C
<b>Insulation Resistance</b>	500 Megaohms Minimum (Measured at 100Vdc)

**ENVIRONMENTAL & MECHANICAL SPECIFICATIONS**

<b>ESD Susceptibility</b>	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
<b>Fine Leak Test</b>	MIL-STD-883, Method 1014, Condition A
<b>Flammability</b>	UL94-V0
<b>Gross Leak Test</b>	MIL-STD-883, Method 1014, Condition C
<b>Lead Integrity</b>	MIL-STD-883, Method 2004
<b>Mechanical Shock</b>	MIL-STD-202, Method 213, Condition C
<b>Moisture Resistance</b>	MIL-STD-883, Method 1004
<b>Moisture Sensitivity</b>	J-STD-020, MSL1
<b>Resistance to Soldering Heat</b>	MIL-STD-202, Method 210, Condition K
<b>Resistance to Solvents</b>	MIL-STD-202, Method 215
<b>Solderability</b>	MIL-STD-883, Method 2003
<b>Temperature Cycling</b>	MIL-STD-883, Method 1010, Condition B
<b>Vibration</b>	MIL-STD-883, Method 2007, Condition A

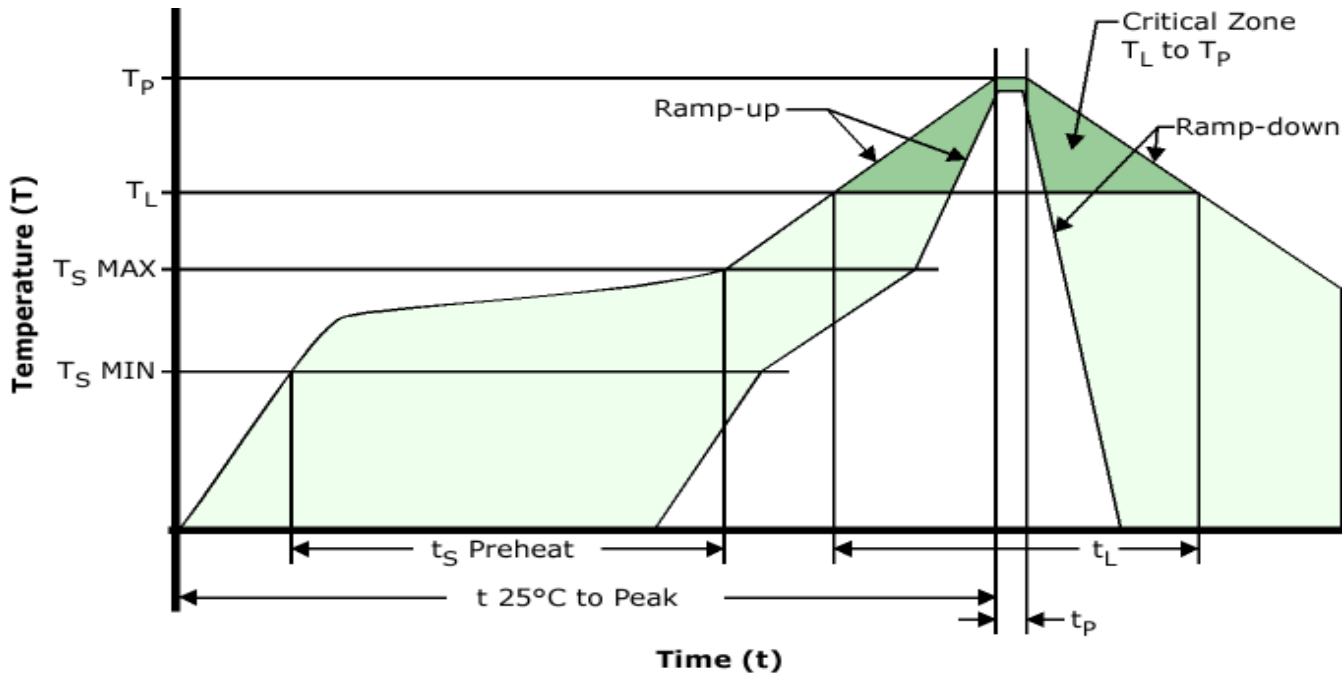
**E1UGA30-15.000M** **MECHANICAL DIMENSIONS (all dimensions in millimeters)**

LINE	MARKING
1	<b>E15.000M</b> <i>E=Ecliptek Designator</i>



# E1UGA30-15.000M [↗](#)

## Recommended Solder Reflow Methods

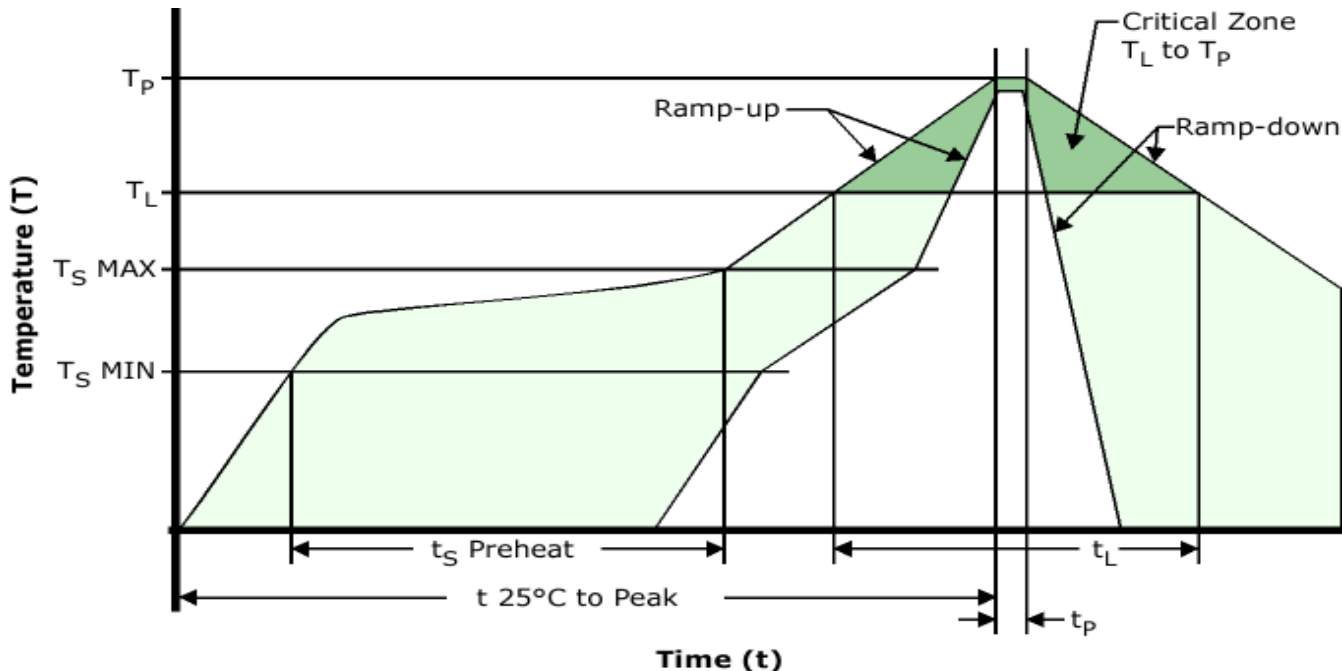


### High Temperature Solder Bath (Wave Solder)

$T_S$ MAX to $T_L$ (Ramp-up Rate)	3°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_S$ MIN)	150°C
- Temperature Typical ( $T_S$ TYP)	175°C
- Temperature Maximum ( $T_S$ MAX)	200°C
- Time ( $t_s$ MIN)	60 - 180 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	3°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	217°C
- Time ( $t_L$ )	60 - 150 Seconds
<b>Peak Temperature (<math>T_P</math>)</b>	260°C Maximum for 10 Seconds Maximum
<b>Target Peak Temperature (<math>T_P</math> Target)</b>	250°C +0/-5°C
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	20 - 40 Seconds
<b>Ramp-down Rate</b>	6°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	8 Minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to back of PCB board and device leads only.

# E1UGA30-15.000M [↗](#)

## Recommended Solder Reflow Methods



### Low Temperature Solder Bath (Wave Solder)

Ts MAX to TL (Ramp-up Rate)	5°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum (Ts MIN)	N/A
- Temperature Typical (Ts TYP)	150°C
- Temperature Maximum (Ts MAX)	N/A
- Time (ts MIN)	30 - 60 Seconds
<b>Ramp-up Rate (TL to TP)</b>	5°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature (TL)	150°C
- Time (tL)	200 Seconds Maximum
<b>Peak Temperature (TP)</b>	245°C Maximum
<b>Target Peak Temperature (TP Target)</b>	245°C Maximum 1 Time / 235°C Maximum 2 Times
<b>Time within 5°C of actual peak (tp)</b>	5 Seconds Maximum 1 Time / 15 Seconds Maximum 2 Times
<b>Ramp-down Rate</b>	5°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	N/A
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to back of PCB board and device leads only.

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to back of PCB board and device leads only.)

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to back of PCB board and device leads only.)